Blakely, Sokoloff, Taylor & Zafman LLP (310) 207-3800 Title: METHOD FOR OPTICAL MODULE PACKAGING OF FLIP CHIP

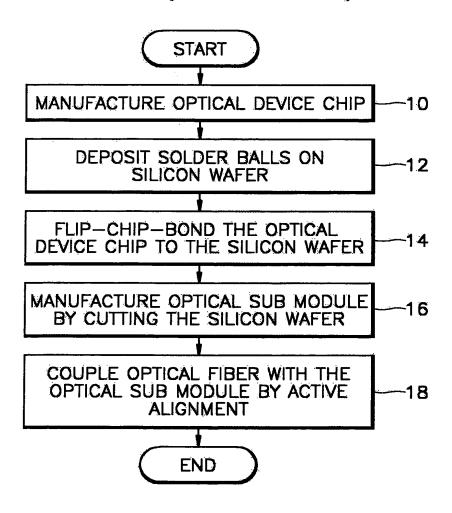
BONDING

1st Named Inventor: Jong-Tae Moon Express Mail No.: EV339905694US

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Docket No.: 2013P036D

## FIG. 1 (PRIOR ART)

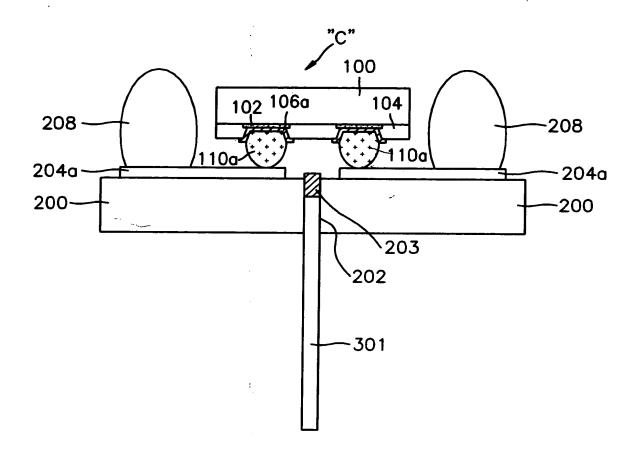


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FIG. 2



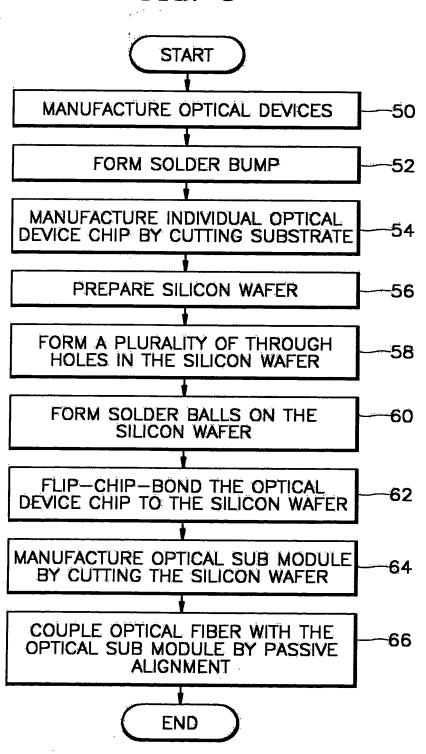
- Blakely, Sokoloff, Taylor & Zafman LLP (310) 207-3800 Title: METHOD FOR OPTICAL MODULE PACKAGING OF FLIP CHIP

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FIG. 3



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FIG. 4

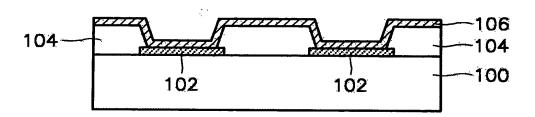


FIG. 5

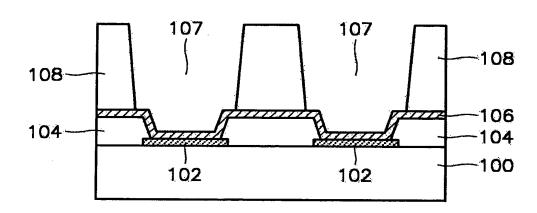
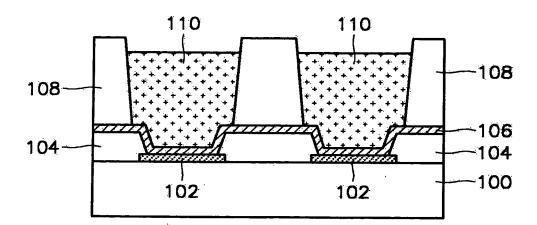


FIG. 6



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FIG. 7

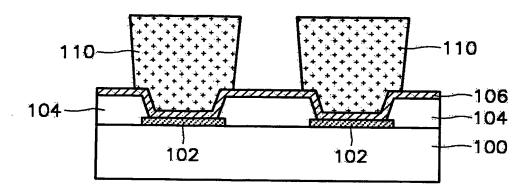


FIG. 8

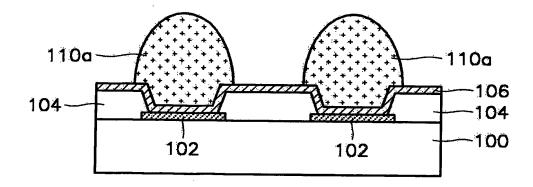
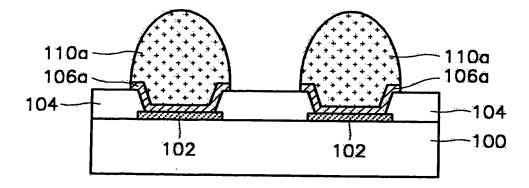


FIG. 9



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FIG. 10

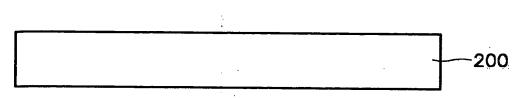


FIG. 11

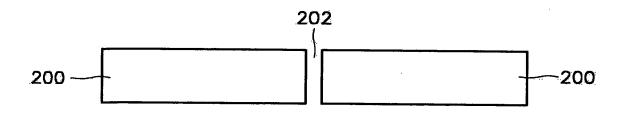


FIG. 12

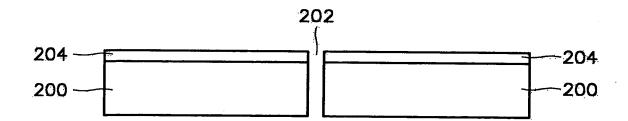
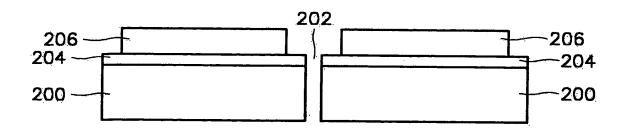


FIG. 13



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FIG. 14

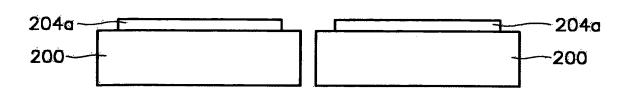


FIG. 15

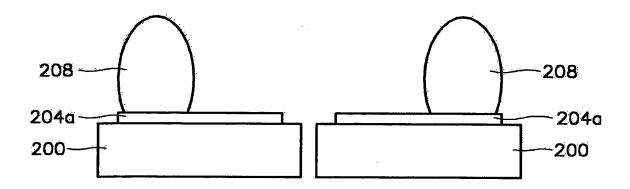


FIG. 16

